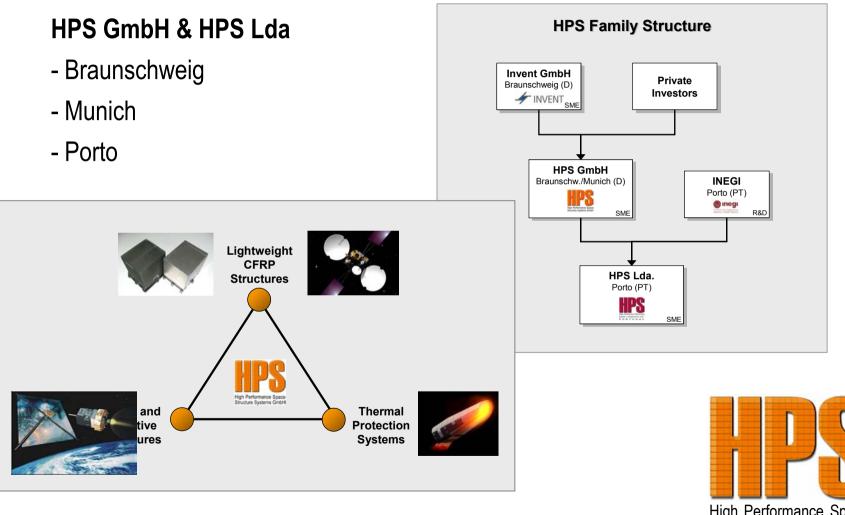


Organic/Inorganic Materials and CFRP Structures Reinforced with Carbon Nanotubes for Space Applications

Felicitas Hepp, Frank Thurecht Noordwijk, 11.10.07



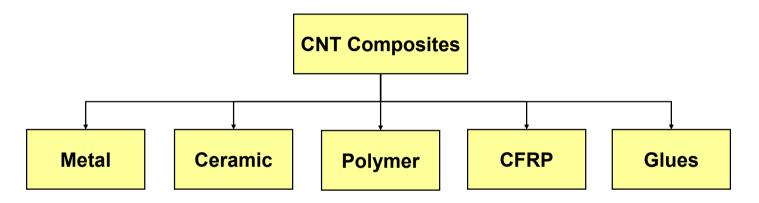




High Performance Space Structure Systems GmbH



Different Materials for Different Applications:



Different Classes and Production Principles:



CNT Based Materials



Ceramic / Metal Applications

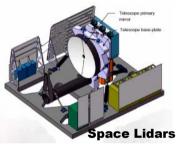
Improvement of:

- > Electrical Conductance
- > Thermal Conductance
- Surface Conductance
- Low CTE
- > Brittleness (Ceramics)
- Damping of Structures



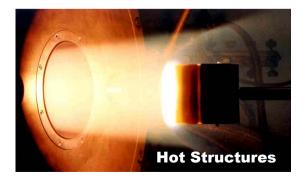


Optical Instruments











CNT Applications in CFRP Products of HPS

> Already Realized / Under Realization:







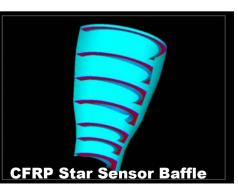
Improvement of:

Primary:

- Electrical Conductivity (inside and on surface)
- > Thermal Conductivity Secondary:
- > Tensile Strength
- Damping of Structures

Envisaged:









Overview on

3 Studies on CNT-based Materials under contract to ESTEC and 1 Study where CNT composites have been used.



"NANOTUBE BASED COMPOSITE MATERIALS" Customer: ESA/ESTEC, (2005 – 2007)

Selecting two model nano-composite systems :

Determining potential space applications SiC matrix

Collecting concepts by CNT composite producers

► Low volume fraction of CNT as reinforcement (1 - 5 %) :

- SiC matrix , (2 production routes)
- Potential Applications: Mirrors, optical benches, "conductive" cermic structures
- ► High volume fraction of CNT, (17 20 %)
 - **Cu matrix** (1 2 vol% Ni)
 - Potential Applications: Heat sinks

Enhancement of properties brought by presence of CNT with respect to bulk matrix presently evaluated.

Main subcontractors to HPS : ASTRIUM (D), BOOSTEC (F), CIRIMAT (F), FHN (D), FutureCarbon (D), NMW (D), SUPSI (CH), TUW (A).

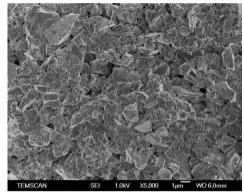


Fig.1: FEG-SEM-image (**5000 X**) of 0.86 vol.% **CNT-SiC Green body** composite before pressureless sintering (Production process by BOOSTEC, Analysis by CIRIMAT)

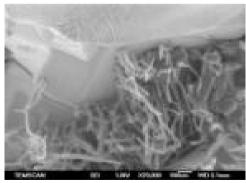
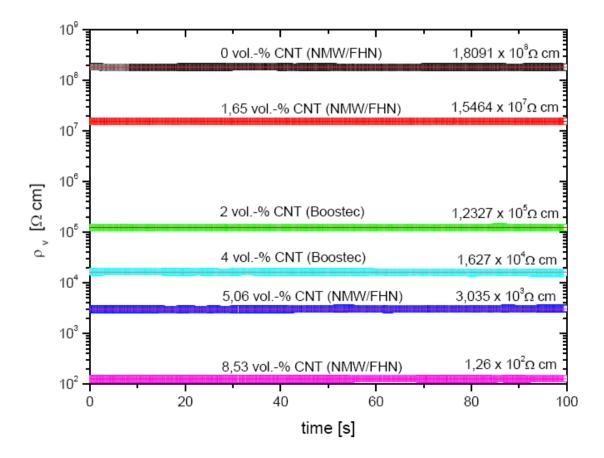


Fig. 2: FEG-SEM-image (**70.000 X**), Fracture surface of 0.86 vol.% **CNT-SiC** composite after **pressureless sintering** (Production process by BOOSTEC, Analysis by CIRIMAT)



CNTM: Examples of First Test Results I (Tests performed by NMW, FHN)

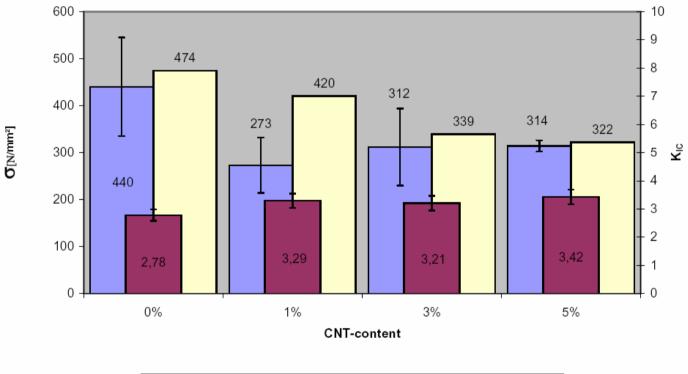
CNT SiC Composite (BOOSTEC, NMW, FHN): Electrical conductivity





CNTM: Examples of First Test Results II (Tests performed by NMW, FHN)

CNT SiC Composite: Fracture toughness and flexural strength

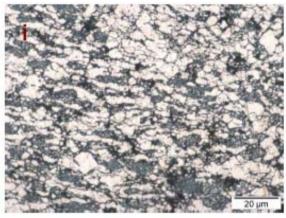


■ Flexural Strength ■ Flexural Strength (valid breaking) ■ KIC by SEVNB



CNTM: Examples of First Test Results III (Tests performed by TUW, TUM)

CNT Cu Composite (TUW): LOM Images (TUW), Thermal Expansion (CTE) Measurements (TUM)



LOM image of hot pressed sample, central area : CNTs visible as agglomerates,

T	samples	α (physical) -150/+150°C [1/K *10 ⁵]	
		measurement 1	measurement 2
	Reference	15,95	15,97
	sample	16,10	16,17
Γ	— Pieces cut —	15,65	15,68
Ι	from hot	15,65	15,67
Γ	pressed	15,46	15,48
Γ	samples	15,22	15,21

CTE measurements of hot pressed samples



"NON CONVENTIONAL MATRIX CARBON NANOTUBES REINFORCED COMPOSITE FOR APPLICATIONS IN SPACE" Customer: ESA/ESTEC (2007 – 2009)

"Skeleton" or "CNT Network" out of carbon nanotubes (paper, felt)

infiltrated with

- polymer matrix (Cyanate Ester, Epoxy)
- metal matrix (Cu, AI, and Alloys thereof)
- ceramic matrix (SiC).

Determining most interesting material / application couples. Developing a sound route for **manufacturing CNT network** as composite preform, Measuring features of developed CNT network (physical and mechanical properties), Developing technologies for CNT network infiltration

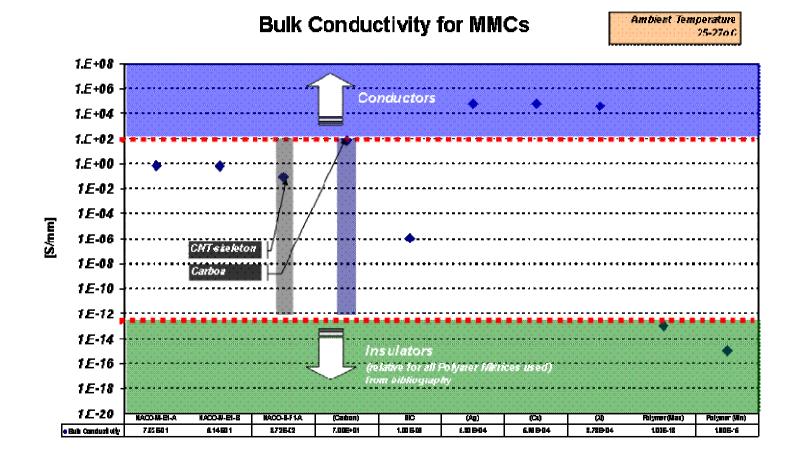
Characterising CNT reinforced composite materials according to targeted applications.

Last Step: Production of demonstrators

Main subcontractors to HPS : ARC Seibersdorf (A), ASTRIUM (D), DLR (D), Electrovac (A), FutureCarbon (D), INEGI (P), PIEP (P), U of Patras (Gr)



Example of First Test Result

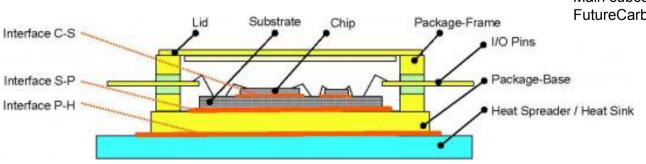




IMPROVEMENT OF THERMAL DISSIPATION BY NANO-MATERIAL Customer: ESA/ESTEC (2007 – 2008)

Epoxy matrices + CNT + other nano-particles: Improving thermal conductivity between electronic chip and substrate.

- 1st task: Identifying possible nano-materials for improving thermal dissipative properties of epoxies: 2 routes
 - Standard space qualified epoxy (semiconductor industry) filled with Ag-microparticles) + CNT
 - Standard epoxy material + nano-particles (BN, Ag-nanoparticles, carbon black)+ CNT
- 2nd task: Breadboarding and testing for thermal/mechanical properties Most performant modified die attach material
 - Validation



Measurement/characterisation of hybrid circuit demonstrator

Main subcontractors to HPS : FutureCarbon (D), KT (D), RHE (D),

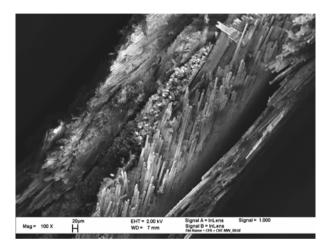


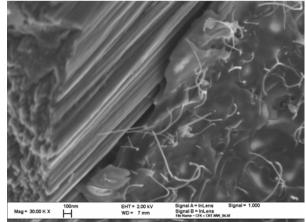
Development of a CFRP Electronic Housing Customer: ESA/ESTEC (2005-2007)

CFRP structures + CNT:

Mechanical strength is only slightly increasing, electrical conductivity \perp to the fibre orientation: increases by 1-2 orders of magnitude.

- → potential for excellent electromagnetic shielding performance
- → better thermal conductivity (good thermal control of hot electronic boards)
- → good electrical conductivity between the plates (grounding).







Thank you for your attention!

Questions?

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